CRS09 Technical Datasheet

Analogue Angular Rate Sensor High Performance MEMS Gyroscope

Features

- Proven and Robust silicon MEMS vibrating ring structure
- FOG-like performance
- Low Bias Instability
- Excellent Angle Random Walk
- Low noise
- Precision analogue output
- Wide range from -40°C to +85°C
- High shock and vibration rejection
- Temperature sensor output for precision thermal compensation
- MEMS frequency output for precision thermal compensation
- RoHS Compliant
- Two rate ranges, two performance options for each

Applications

- Platform Stabilization
- Precision Surveying
- Maritime Guidance and Control
- Gyro-compassing and Heading Control
- Autonomous Vehicles and ROVs
- Rail Track monitoring
- Robotics

1 General Description

CRS09 provides the optimum solution for rate range applications where bias instability, angle random walk and low noise are of critical importance.

The latest inductive MEMS gyro sensor element is combined with precision discrete electronics to achieve high stability and low noise, making the CRS09 a viable alternative to fibre-optic and dynamically tuned gyros.

An on board temperature sensor and the resonant frequency of the MEMS enables additional external conditioning to be applied to the CRS09 by the host, enhancing the performance even further. Test data for Bias and Scale Factor can be provided with each gyroscope enabling this compensation to be implemented without the need for further calibration.

Typical applications include downhole surveying, precision platform stabilization, ship stabilisation, ship guidance and control, autonomous vehicles and high-end AHRS.

Whatever your application, the unique and patented silicon ring technology gives advanced and stable performance over time and temperature, overcoming mount sensitivity problems associated with simple beam or tuning fork based sensors.

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Analogue Angular Rate Sensor

High Performance MEMS Gyroscope

2 Ordering Information

3 Specifi cation

Unless otherwise specified the following specification values assume Vdd = 4.75 to $5.25V$ over the temperature range -40 to $+85^{\circ}$ C.

4 Characteristics

5 Auxillary Output Signals

Note 1: The product must not be subjected to temperatures outside the recommended storage temperature range at any time.

Note 2: Do not drop the device onto a hard surface from a height exceeding 300mm.

6 Typical Performance Characteristics

Graphs showing typical performance characteristics for CRS09 are below. **Note:** Typical data is with the device powered from a 5.0V supply, unless stated otherwise.

Bias Characteristics

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Figure 6.2 Bias Error over Temperature for CRS09-11, including the Bias Setting Error at 23°C

Figure 6.5 Scale Factor Error over Temperature for CRS09-01, including the Setting Error at 23°C

Figure 6.7 Scale Factor Error over Temperature for CRS09-11, including the Setting Error at 23°C

20

Chamber Temperature (°C)

 $\bf{0}$

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Figure 6.6 Scale Factor Error over Temperature for CRS09-02, including the Setting Error at 23°C

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 $\overline{80}$

60

40

 $\frac{1}{100}$

 \mathbf{a}

 0.6

 0.4

 0.2

 ϵ

 -0.2

 -0.4

 -0.6

 -0.5

 $\frac{1}{-60}$

 -40

 -20

Scale Factor Error (%)

Non-Linearity Error

Figure 6.9 Non-Linearity Error (Maximum) over Temperature for CRS09-01 and CRS09-11

Figure 6.11 Non-Linearity Error versus Applied Rate at 23°C, CRS09-01 and CRS09-11.

 $\bf{0}$

Applied Rate (⁰/sec)

40

 120

80

160

200

Figure 6.10 Non-Linearity Error versus Applied Rate at -40°C, CRS09-01 and CRS09-11

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 0.1

n ns

0.06

 0.04

 0.02

 -0.02

 -0.0

 -0.06

 -0.08

 -0.1
 -200

 -120

 -80

 -40

 -160

Non-linearity Error (%)

Non-Linearity Error Continued

Figure 6.13 Non-Linearity Error (Maximum) over Temperature for CRS09-02 and CRS09-12

Figure 6.15 Non-Linearity Error versus Applied Rate at 23°C, CRS09-02 and CRS09-12

 $\mathbf 0$

Applied Rate (⁰/sec)

20

40

60

80

100

Figure 6.14 Non-Linearity Error versus Applied Rate at -40°C, CRS09-02 and CRS09-12

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 0.1

 0.08

 0.06

 0.04

 0.02

 -0.02

 -0.0

 -0.06

 -0.08

 -0.1
-100

 -60

 -80

 -40

 -20

Non-linearity Error (%)

Frequency Output

Figure 6.18 Frequency Output variation over Temperature for CRS09-11

Allan Variance Data

Figure 6.21 Typical Allan Variance Data for CRS09-01 and CRS09-11

Temperature Sensor Characteristics

Figure 6.22 Typical Allan Variance Data for CRS09-02 and CRS09-12

Figure 6.24 Temperature Sensor Output with respect to 0V (GND) against Chamber Temperature for CRS09-01 and CRS09-11

Temperature Sensor Characteristics Continued

Figure 6.25 Temperature Sensor Output with respect to VRef against Chamber Temperature for CRS09-01 and CRS09-11

Figure 6.27 Temperature Sensor Output with respect to 0V (GND) against Chamber Temperature for CRS09-02 and CRS09-12

Figure 6.26 Temperature Sensor Error against Chamber Temperature for CRS09-02 and CRS09-12

Voltage Reference Output (VRef)

Figure 6.29 Voltage Reference variation with Temperature for CRS09-01 and CRS09-11

Figure 6.30 Voltage Reference variation with Temperature for CRS09-02 and CRS09-12

7 Interfacing

Figure 7.1 Recommended Interfacing

The table below provides connection details.

7.1 Temperature Sensor

The temperature sensor uses the LM20B device, internally connected as shown in Figure 8.7.

Figure 7.2 Temperature Sensors

The output at 0°C is typically +1.864V with respect to GND. The temperature coefficient is typically -11.77 mV/°C.

The output can be measured with respect to GND or can be put through a differential input instrumentation amplifier, referenced to the Ref pin, in which case the offset at 0°C is typically -0.536V. At +25°C, the output is typically -0.830V with respect to Ref. The temperature sensors are not intended for use as a thermometer, since they are not calibrated on the Celsius scale. They are intended only as a temperature reference for thermal compensation techniques.

7.2 Rate and Ref Outputs

Both the Rate and the Ref outputs are passed through a simple RC low pass filter before the output pins. The resistor value is 100 ohms. The capacitor value is 0.1μF.

It is recommended that the Rate Output (signal High or +) is differentially sensed using a precision instrumentation amplifier, referenced to the Ref output (signal Low or -).

The Offset of the instrumentation amplifier should be derived from the host stage (e.g. derived from the ADC Ref Voltage) or from the signal ground if the following stage is an analogue stage.

7.3 Frequency Outputs

This is CMOS Digital (74HC series) compatible digital output at two times the frequency of the sensor head. It is provided to give an indication of the temperature of the MEMS sensor head. The nominal frequency is 28 KHz with a typical temperature coefficient of -0.8 Hz/°C.

The signal is protected with a 1Kohm resistor before being output from the CRS09. It is recommended that this signal is buffered with a CMOS Schmitt Gate such as 74HC12, or TC7S14F. The signal can be used to accurately measure the temperature of the MEMS structure.

An example of measuring the MEMS temperature is to use a precision crystal oscillator (operating at a very high frequency, for example 20, 40 or 60 MHz) to measure the frequency of the ring by measuring the time (oscillator clock cycles) to count to a defined number of ring cycles.

8 Glossary of Terms

9 Part Markings

Figure 9.1 Part Marking

Table 9.1 Serial Number Code

10 Silicon MEMS Ring Sensor (Gyro)

The silicon MEMS ring is 6mm diameter by 100μm thick, fabricated by Silicon Sensing Systems using a DRIE (Deep Reactive Ion Etch) bulk silicon process. The ring is supported in free-space by sixteen pairs of 'dog-leg' shaped symmetrical legs which support the ring from the supporting structure on the outside of the ring.

Figure 10.1 Silicon MEMS Ring

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The bulk silicon etch process and unique patented ring design enable close tolerance geometrical properties for precise balance and thermal stability and, unlike other MEMS gyros, there are no small gaps to create problems of interference and stiction. These features contribute significantly to CRS09's bias and scale factor stability over temperature, and vibration immunity. Another advantage of the design is its inherent immunity to acceleration induced rate error, or 'g-sensitivity'.

Figure 10.2 MEMS Sensor Head

The ring is essentially divided into 8 sections with two conductive tracks in each section. These tracks enter and exit the ring on the supporting legs. The silicon ring is bonded to a glass pedestal which in turn is bonded to a glass support base. A magnet, with upper and lower poles, is used to create a strong and uniform magnetic field across the silicon ring. The complete assembly is mounted within a hermetic can with a high internal vacuum.

The tracks along the top of the ring form two pairs of drive tracks and two pairs of pick-off tracks. Each section has two loops to improve drive and pick-off quality.

One pair of diametrically opposed tracking sections, known as the Primary Drive PD section, is used to excite the $cos2\theta$ mode of vibration on the ring. This is achieved by passing current through the tracking, and because the tracks are within a magnetic field causes motion on the ring. Another pair of diametrically opposed tacking sections is known as the Primary Pick-off PP section is used to measure the amplitude and phase of the vibration on the ring. The Primary Pick-off sections are in the sections 90° to those of the Primary Drive sections. The drive amplitude and frequency is controlled by a precision closed loop electronic architecture with the frequency controlled

by a Phase Locked Loop (PLL), operating with a Voltage Controlled Oscillator (VCO), and amplitude controlled with an Automatic Gain Control (AGC) system. The primary loop therefore establishes the vibration on the ring and the closed loop electronics is used to track frequency changes and maintain the optimal amplitude of vibration over temperature and life. The loop is designed to operate at about 14kHz.

Figure 10.3 Primary Vibration Mode

Having established the $cos2\theta$ mode of vibration on the ring, the ring becomes a Coriolis Vibrating Structure Gyroscope. When the gyroscope is rotated about its sense axis the Coriolis force acts tangentially on the ring, causing motions at 45° displaced from the primary mode of vibration. The amount of motion at this point is directly proportional to the rate of turn applied to the gyroscope. One pair of diametrically opposed tracking sections, known as the Secondary Pick-off SP section, is used to sense the level of this vibration. This is used in a secondary rate nulling loop to apply a signal to another pair of secondary sections, known as the Secondary Drive SD. The current applied to the Secondary Drive to null the secondary mode of vibration is a very accurate measure of the applied angular rate. All of these signals occur at the resonant frequency of the ring. The Secondary Drive signal is demodulated to baseband to give a voltage output directly proportional to the applied rate in free space.

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Figure 10.4 Secondary Vibration Mode

The closed loop architecture on both the primary and secondary loops result is excellent bias, scale factor and non-linearity control over a wide range of operating environments and life. The dual loop design, introduced into this new Sensor Head design, coupled with improved geometric symmetry results in excellent performance over temperature and life. The discrete electronics employed in CRS09, ensures that performance is not compromised.

Notes

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